



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C101JB8NNNL
- Description : CAP, 100pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

	<u>CL</u> <u>10</u> <u>C</u> ① ② ③	101         J         B         8         N         N           ④         5         6         7         8         9	<u>N</u> <u>L</u> 100 11
1 Series	Samsung Multi-layer Ceramic Capacitor		
<ol> <li>Size</li> </ol>	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1 mm
③ Dielectric	C0G	Inner electrode	Ni
④ Capacitance	<b>100</b> pF	Termination	Cu
<b>⑤</b> Capacitance	±5 %	Plating	Sn 100% (Pb Free)
tolerance		9 Product	Normal
Rated Voltage	50 V	10 Special	Reserved for future use
⑦ Thickness	0.8 ± 0.1 mm	① Packaging	Cardboard Type, 13" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition	
Capacitance	Within specified tolerance	1M±±10% 0.5~5Vrms	
Q	1000 min		
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	300% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	COG		
Characterisitcs	(From -55 $^\circ\!\!\mathbb{C}$ to 125 $^\circ\!\!\mathbb{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\mathbb{C}$ )		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change :	Bending to the limit (1mm)	
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5℃, 3±0.3sec.	
		(preheating : 80~120℃ for 10~30sec.)	
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger		
	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change :	Amplitude : 1.5mm
	within $\pm 2.5\%$ or $\pm 0.25_{pF}$ whichever is larger	From 10H₂ to 55H₂ (return : 1min.)
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)
Moisture	Capacitance change :	With rated voltage
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs
	Q : 200 min	
	IR : 500Mohm or 25Mohm $\cdot \mu F$	
	Whichever is Smaller	
High Temperature	Capacitance change :	With 200% of the rated voltage
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature
	Q : 350 min	1000+48/-0hrs
	IR : 1000Mohm or 50Mohm $\cdot \mu F$	
	Whichever is Smaller	
Temperature	Capacitance change :	1 cycle condition
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperature $\rightarrow$ 25 °C
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C
		5 cycle test

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.